

JCS 706

JC 09/847667		Class	Subcla
		09	01/01
		ISSUE CLASSIFICAT	

U.S. UTILITY Patent Application

Q2 SCANNED	O.I.P.E. Q.A. AA	PATENT DATE
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APPLICATION NO. 09/847667	CONT/PRIOR	CLASS 257	SUBCLASS 277	ART UNIT 2822 2827	EXAMINER Mitche II
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APPLICANTS
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TITLE
Method for bonding wafers to produce stacked integrated circuits

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL		CROSS REFERENCE(S)			
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)		
INTERNATIONAL CLASSIFICATION					
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TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____	(Primary Examiner) _____ (Date) _____			ISSUE FEE	
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